

ABSTRACT

Sub 5
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10 A printed circuit board and a method for manufacturing the same that facilitates the formation of an upper surface pattern and prevents a lower surface metal foil from being damaged when forming a blind via hole with a laser is provided. A lower surface and an upper surface of an insulative substrate (5) are respectively coated with a lower surface metal foil (220) and an upper surface metal foil (210), the thickness of which is less than that of the lower surface metal foil (220). Next, an opening (213) is formed in the upper surface metal foil at a location corresponding to a blind via hole formation portion (35) of the insulative substrate. A blind via hole (3), the bottom of which is the lower surface metal foil, is formed by emitting a laser (8) against the blind via hole formation portion (35) through the opening (213). Then, a metal plating film (23) is applied to the wall of the blind via hole (3), and an upper surface pattern (21) and a lower surface pattern (22) are formed through etching.

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